

GENERAL PROPERTIES

	PROPERTY	TYPICAL VALUE	DIRECTION	CONDITION	TEST METHOD
Thermal	Glass Transition Temperature, Tg	160	°C	A	DMA IPC-TM-650 2.4.24.2
	Thermal Expansion, Z CTE	37	ppm/°C	A	Before Tg, IPC-TM-650 2.4.24
		230	ppm/°C	A	After Tg, IPC-TM-650 2.4.24
	Decomposition Temperature, Td	348	°C	A	TMA IPC-TM650 2.4.24.6
	Delamination Time, T260	60	minutes	A	TMA IPC-TM650 2.4.24
	Delamination Time, T288	20	minutes	A	TMA IPC-TM650 2.4.24
Electrical	Dielectric Constant (Dk)	4.6	-	1 GHz	IPC-TM-650 2.5.5.9
		4.9	-	1 MHz	IPC-TM-650 2.5.5.9
	Dissipation Factor (Df)	0.011	-	1 GHz	IPC-TM-650 2.5.5.9
		0.009	-	1 MHz	IPC-TM-650 2.5.5.9
	Volume Resistivity	1.50E+08	MΩ-cm	After moisture resistance	IPC-TM-650 2.5.17.1
	Surface Resistivity	3.50E+07	MΩ	After moisture resistance	IPC-TM-650 2.5.17.1
	Dielectric Breakdown	45+NB	kV	D-48/50+D-0.5/23	IPC-TM-650 2.5.6
Physical	Thermal Conductivity	0.74	W/m·K	100°C	ASTM D5470
	Water Absorption	0.09	%	D-24/23	IPC-TM-650 2.6.2.1
	Copper Peel Strength	1.3 (7.4)	N/mm (lb/in.)	after solder float 1 oz. EDC Foil	IPC-TM-650 2.4.8
	Flammability	94V-0	-	A	UL

PRODUCT CONTACTS

FRED HICKMAN

VP of NA HSD OEM Marketing
 Email: Fredhickman@syst.com.cn
 Phone: 602-722-4053

Web: www.shengyi-usa.com